

Dynardo Workshop

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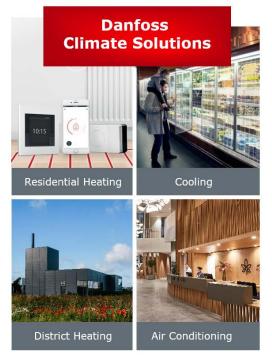


Advances in MDO at Danfoss Introduction

- Context:
 - Another MDO example
 - Further MDO development
 - Family parametrization
 - System model
 - Other business unit examples:
 - HEX: dimple optimization
 - SiliconPower: cooling channel optimization





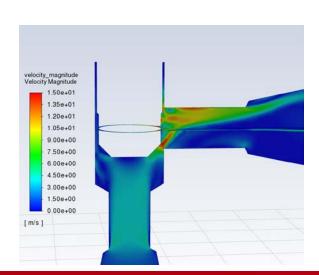


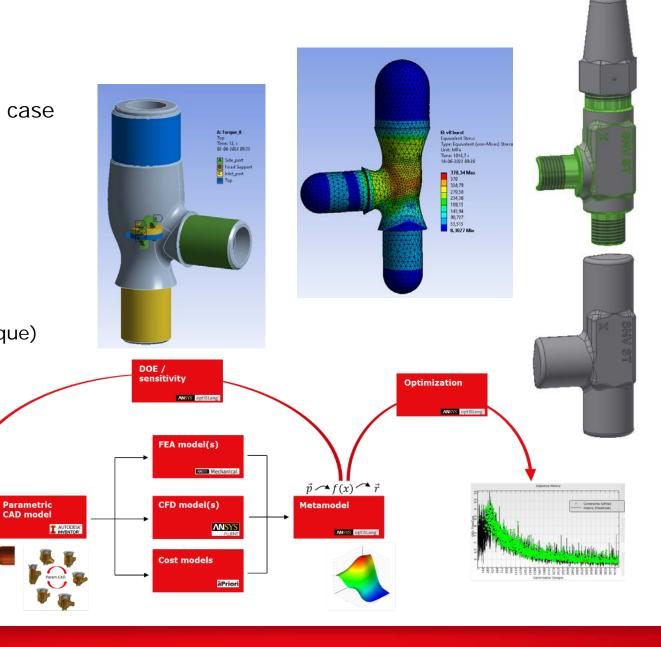


Danfoss RAC: SNV optimization

- Multidisciplinary optimization
 - Similar implementation as previous NRV case
 - FEA, CFD, cost:
 - Torque max load
 - Burst pressure
 - Flow capacity
 - Optimization objectives/constraints:
 - Minimize cost (or weight+height)
 - Maintain requirements (burst, capacity, torque)

Design



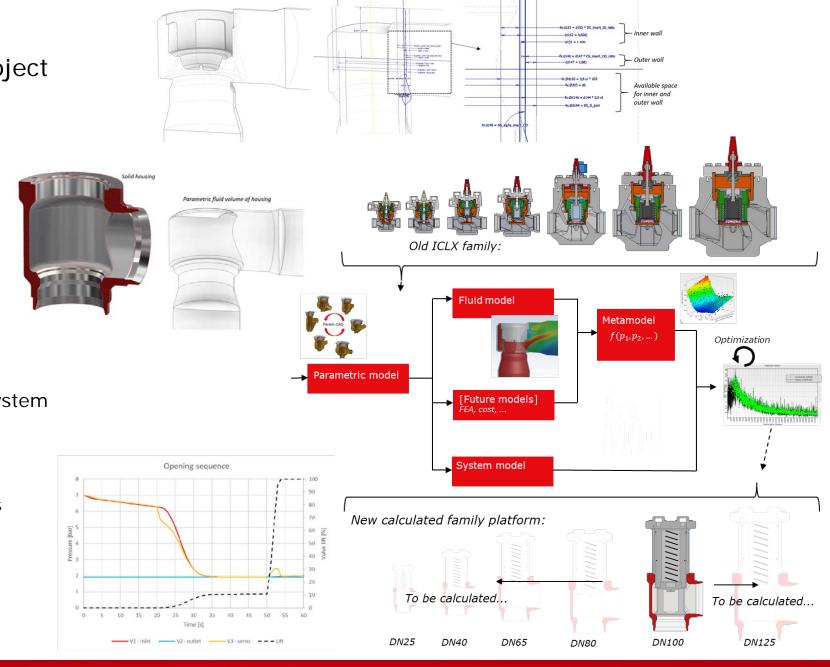




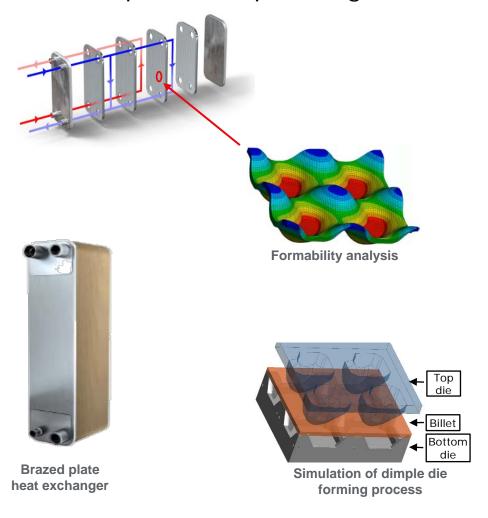
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Danfoss RAC: Family automation project

- Project:
 - How to do MDO on a full valve family?
 - · Parametric geometry for full family size
 - Include system model in loop
- Parametric CAD model
 - Based on housing platform
 - Parametrization: Relative to housing
- System model
 - Interaction with customer refrigeration system (hot gas equalization)
 - Linked to CFD MOP
 - Transient valve behaviour
 - Evaluation of several operating conditions
- MOP study:
 - MOP to fit entire family (lift and size)
 - Accurate MOP for each size (lift only)

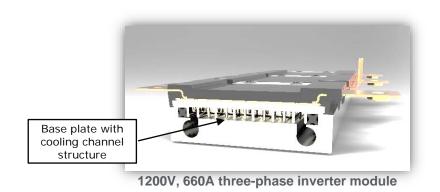


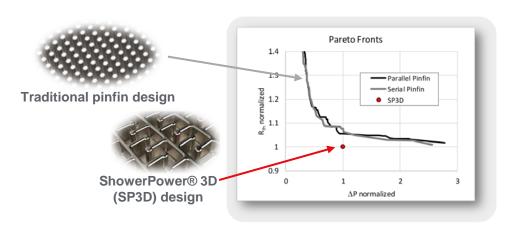
Danfoss HEX: Optimal dimple designs for new brazed plate heat exchanger



- Optimal design: best compromise between the enhancement of the total heat transfer and the reduction in the overall pressure drop.
- The relationship between thermal and fluid dynamic performance, manufacturing feasibility, and cost was explored upfront in concept development.
 - Simulations of the sheet metal forming process were included in the optimization workflow.
- Evaluated design robustness considering performance cost and formability.
- Multi-disciplinary team to cut through barriers to good design.

Danfoss SiliconPower: Optimized cooling channel structure for high-power density inverter module





- **Optimal design**: best compromise between the reduction of thermal resistance (R_{th}) and the reduction in the overall pressure drop (Δp) .
- Comparison of two topologies: exploration of the pinfin design space (Pareto solutions, see figure) vs. current SP3D design.
 - There is no pinfin design that can outperform the current SP3D solution (for the given operating conditions).
- Exploration of various SP3D design alternatives; predicted performance improvement if overcoming current manufacturing limitations.

Backup slides

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